Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceed the OCM data sheet.

Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
  - Class Q Military
  - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)

  • Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.

SN74LS174

Hex D Flip-Flop

The LSTTL/MSI SN74LS174 is a high speed Hex D Flip-Flop. The device is used primarily as a 6-bit edge-triggered storage register. The information on the D inputs is transferred to storage during the LOW to HIGH clock transition. The device has a Master Reset to simultaneously clear all flip-flops. The LS174 is fabricated with the Schottky barrier diode process for high speed and is completely compatible with all ON Semiconductor TTL families.

- Edge-Triggered D-Type Inputs
- Buffered-Positive Edge-Triggered Clock
- Asynchronous Common Reset
- Input Clamp Diodes Limit High Speed Termination Effects
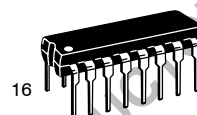
GUARANTEED OPERATING RANGES

Symbol	Parameter	Min	Typ	Max	Unit
V_{CC}	Supply Voltage	4.75	5.0	5.25	V
T_A	Operating Ambient Temperature Range	0	25	70	°C
I_{OH}	Output Current – High			−0.4	mA
I_{OL}	Output Current – Low			8.0	mA

ON Semiconductor™

http://onsemi.com

LOW POWER SCHOTTKY

16

1

PLASTIC N SUFFIX CASE 648

16

1
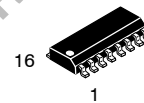
SOIC D SUFFIX CASE 751B

16

1
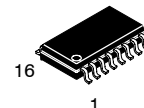
SOEIAJ M SUFFIX CASE 966

ORDERING INFORMATION

Device	Package	Shipping
SN74LS174N	16 Pin DIP	2000 Units/Box
SN74LS174D	SOIC−16	38 Units/Rail
SN74LS174DR2	SOIC−16	2500/Tape & Reel
SN74LS174M	SOEIAJ−16	See Note 1
SN74LS174MEL	SOEIAJ−16	See Note 1

1. For ordering information on the EIAJ version of the SOIC package, please contact your local ON Semiconductor representative.

SN74LS174

CONNECTION DIAGRAM DIP (TOP VIEW)

V_{CC}	Q_5	D_5	D_4	Q_4	D_3	Q_3	CP
16	15	14	13	12	11	10	9

1	2	3	4	5	6	7	8
$\overline{MR}$	Q_0	D_0	D_1	Q_1	D_2	Q_2	GND
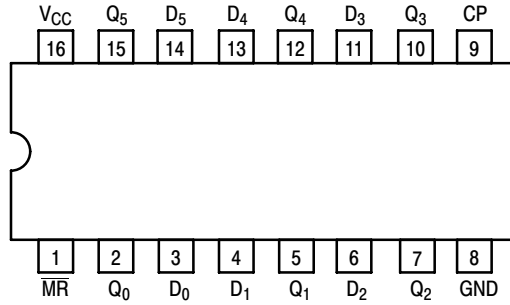
NOTE:
The Flatpak version has the same pinouts (Connection Diagram) as the Dual In-Line Package.

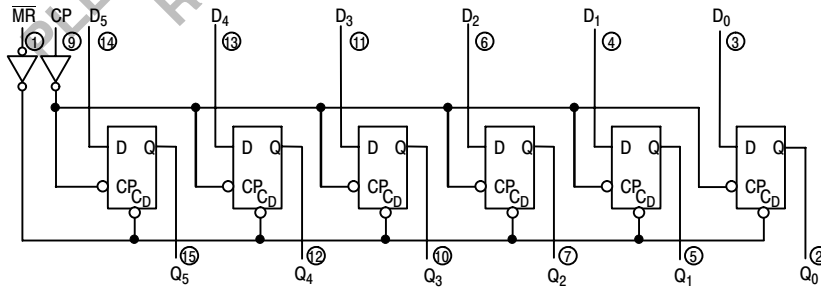| PIN NAMES		LOADING (Note a)	
		HIGH	LOW
$D_0 - D_5$	Data Inputs	0.5 U.L.	0.25 U.L.
CP	Clock (Active HIGH Going Edge) Input	0.5 U.L.	0.25 U.L.
$\overline{MR}$	Master Reset (Active LOW) Input	0.5 U.L.	0.25 U.L.
$Q_0 - Q_5$	Outputs	10 U.L.	5 U.L.

NOTES:
   a) 1 TTL Unit Load (U.L.) = 40 μA HIGH/1.6 mA LOW.

LOGIC SYMBOL
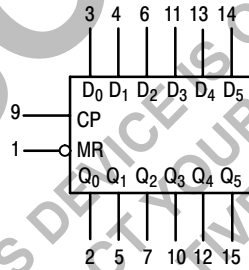
V_{CC} = PIN 16
GND = PIN 8

LOGIC DIAGRAM

V_{CC} = PIN 16
GND = PIN 8

◯ = PIN NUMBERS

SN74LS174

FUNCTIONAL DESCRIPTION

The LS174 consists of six edge-triggered D flip-flops with individual D inputs and Q outputs. The Clock (CP) and Master Reset ($\overline{MR}$) are common to all flip-flops.

Each D input's state is transferred to the corresponding flip-flop's output following the LOW to HIGH Clock (CP) transition.

A LOW input to the Master Reset ($\overline{MR}$) will force all outputs LOW independent of Clock or Data inputs. The LS174 is useful for applications where the true output only is required and the Clock and Master Reset are common to all storage elements.

TRUTH TABLE

Inputs (t = n, $\overline{MR}$ = H)	Outputs (t = n+1) Note 1
D	Q
H	H
L	L

Note 1: t = n + 1 indicates conditions after next clock.

DC CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE (unless otherwise specified)

Symbol	Parameter	Limits			Unit	Test Conditions
		Min	Typ	Max		
V_{IH}	Input HIGH Voltage	2.0			V	Guaranteed Input HIGH Voltage for All Inputs
V_{IL}	Input LOW Voltage			0.8	V	Guaranteed Input LOW Voltage for All Inputs
V_{IK}	Input Clamp Diode Voltage		−0.65	−1.5	V	V_{CC} = MIN, I_{IN} = −18 mA
V_{OH}	Output HIGH Voltage	2.7	3.5		V	V_{CC} = MIN, I_{OH} = MAX, V_{IN} = V_{IH} or V_{IL} per Truth Table
V_{OL}	Output LOW Voltage		0.25	0.4	V	I_{OL} = 4.0 mA	V_{CC} = V_{CC} MIN, V_{IN} = V_{IL} or V_{IH} per Truth Table
			0.35	0.5	V	I_{OL} = 8.0 mA	
I_{IH}	Input HIGH Current			20	μA	V_{CC} = MAX, V_{IN} = 2.7 V
				0.1	mA	V_{CC} = MAX, V_{IN} = 7.0 V
I_{IL}	Input LOW Current			−0.4	mA	V_{CC} = MAX, V_{IN} = 0.4 V
I_{OS}	Short Circuit Current (Note 2)	−20		−100	mA	V_{CC} = MAX
I_{CC}	Power Supply Current			26	mA	V_{CC} = MAX

2. Not more than one output should be shorted at a time, nor for more than 1 second.

Note: the watermark reads "OBSOLETE — THIS DEVICE IS OBSOLETE — PLEASE CONTACT YOUR ON SEMICONDUCTOR REPRESENTATIVE FOR INFORMATION"

SN74LS174

AC CHARACTERISTICS ($T_A = 25°C$)

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
f_{MAX}	Maximum Input Clock Frequency	30	40		MHz	
t_{PHL}	Propagation Delay, $\overline{MR}$ to Output		23	35	ns	$V_{CC} = 5.0$ V $C_L = 15$ pF
t_{PLH} t_{PHL}	Propagation Delay, Clock to Output		20 21	30 30	ns	

AC SETUP REQUIREMENTS ($T_A = 25°C$)

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
t_W	Clock or $\overline{MR}$ Pulse Width	20			ns	
t_s	Data Setup Time	20			ns	$V_{CC} = 5.0$ V
t_h	Data Hold Time	5.0			ns	
t_{rec}	Recovery Time	25			ns	

AC WAVEFORMS
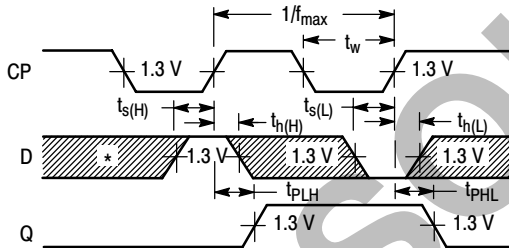
*The shaded areas indicate when the input is permitted to change for predictable output performance.

Figure 1. Clock to Output Delays, Clock Pulse Width, Frequency, Setup and Hold Times Data to Clock
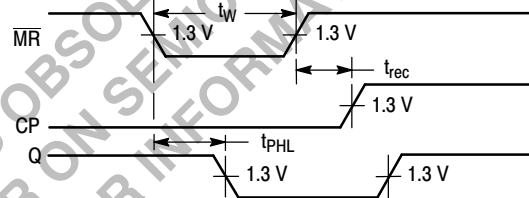
Figure 2. Master Reset to Output Delay, Master Reset Pulse Width, and Master Reset Recovery Time

DEFINITIONS OF TERMS

SETUP TIME (t_s) — is defined as the minimum time required for the correct logic level to be present at the logic input prior to the clock transition from LOW to HIGH in order to be recognized and transferred to the outputs.

HOLD TIME (t_h) — is defined as the minimum time following the clock transition from LOW to HIGH that the logic level must be maintained at the input in order to ensure continued recognition. A negative HOLD TIME indicates that the correct logic level may be released prior to the clock transition from LOW to HIGH and still be recognized.

RECOVERY TIME (t_{rec}) — is defined as the minimum time required between the end of the reset pulse and the clock transition from LOW to HIGH in order to recognize and transfer HIGH Data to the Q outputs.

SN74LS174

PACKAGE DIMENSIONS

N SUFFIX
PLASTIC PACKAGE
CASE 648–08
ISSUE R
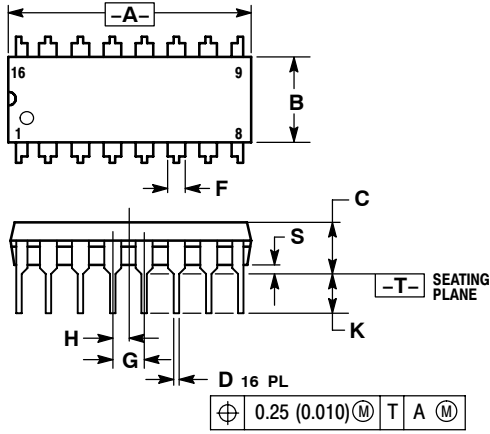
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

PACKAGE DIMENSIONS

D SUFFIX
PLASTIC SOIC PACKAGE
CASE 751B–05
ISSUE J
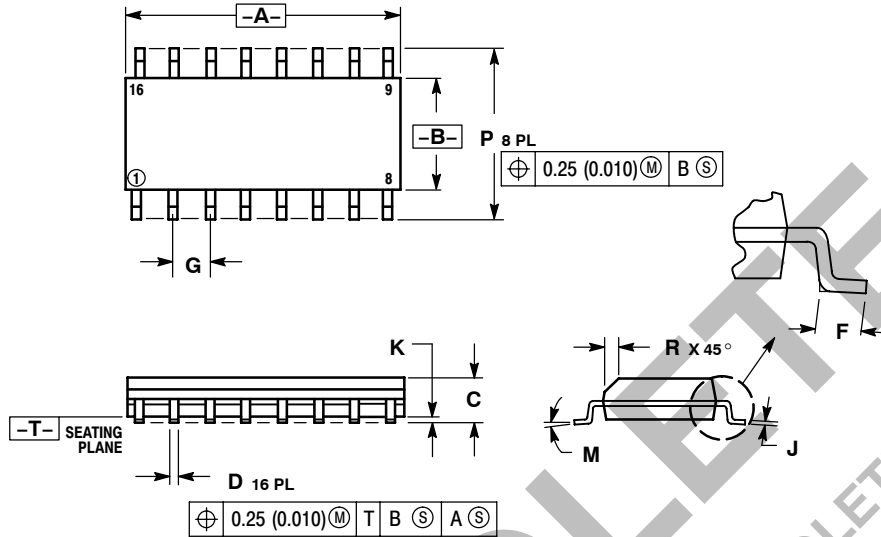
P 8 PL

⊕ | 0.25 (0.010) Ⓜ | B Ⓢ

⊕ | 0.25 (0.010) Ⓜ | T | B Ⓢ | A Ⓢ

D 16 PL

–T– SEATING PLANE

R X 45°

NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0 °	7 °	0 °	7 °
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

PACKAGE DIMENSIONS

M SUFFIX
SOEIAJ PACKAGE
CASE 966–01
ISSUE O
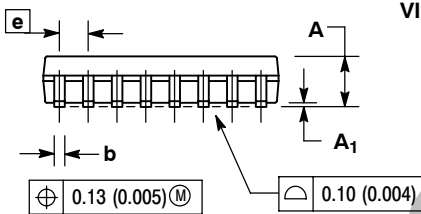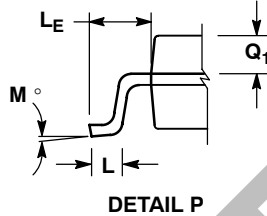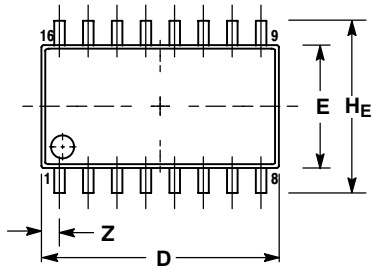
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A_1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H_E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L_E	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q_1	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031

PUBLICATION ORDERING INFORMATION